

**ABSTRACT****LEAD FRAME AND METHOD OF  
MANUFACTURING THE LEAD FRAME**

5           A method for manufacturing a lead frame including the steps of  
electrocleaning the surface of a thin plate material, electropolishing the  
electrocleaned thin plate material, removing inclusions on the surface of the  
electropolished thin plate material, rinsing the inclusion-removed thin plate  
material with an acidic solution, and forming multi-plated layers on the rinsed  
10 material. The lead frame manufactured by the method has 5 or less inclusions  
each having approximately  $1\ \mu\text{m}$ , on the surface area of  $1600\ \mu\text{m}^2$ , which  
impede a wire bonding property or solder wettability of the lead frame.

FIG. 5